AMD FINANCIAL ANALYST DAY 2025

Mark Papermaster
EVP & CTO

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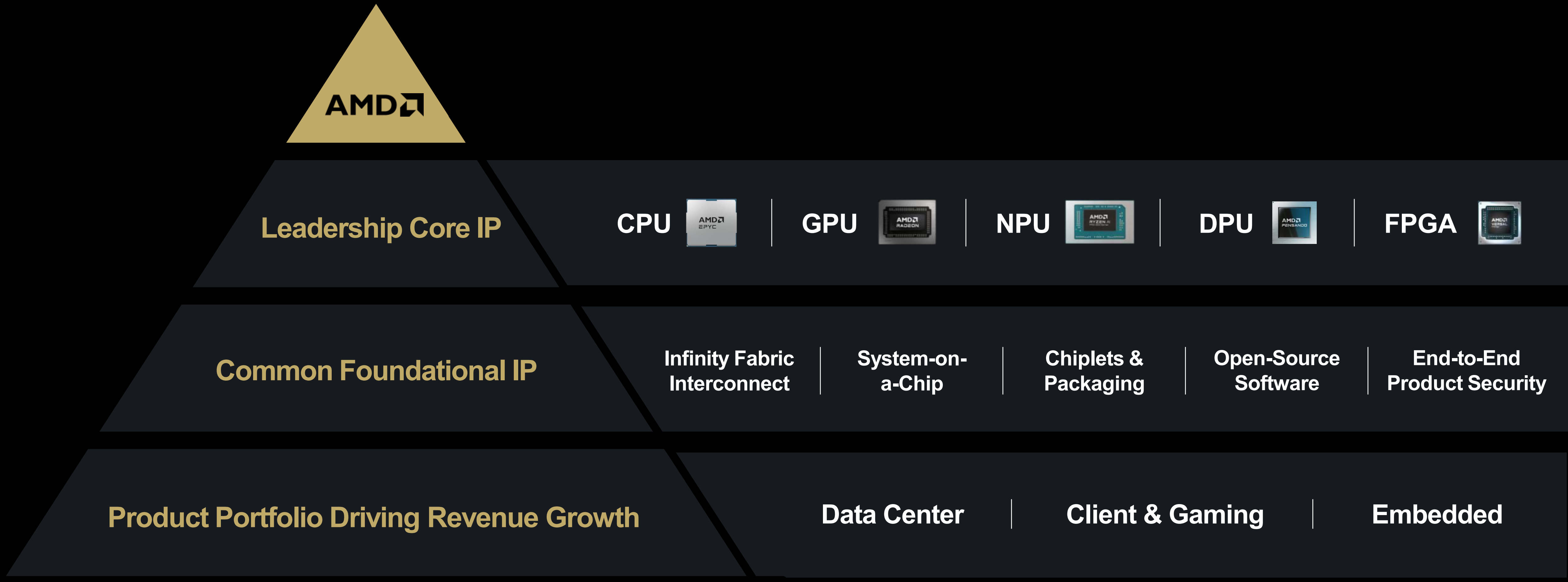
Industry’s Broadest Solution Portfolio



Leadership Core IP

CPU | GPU | NPU | DPU | FPGA

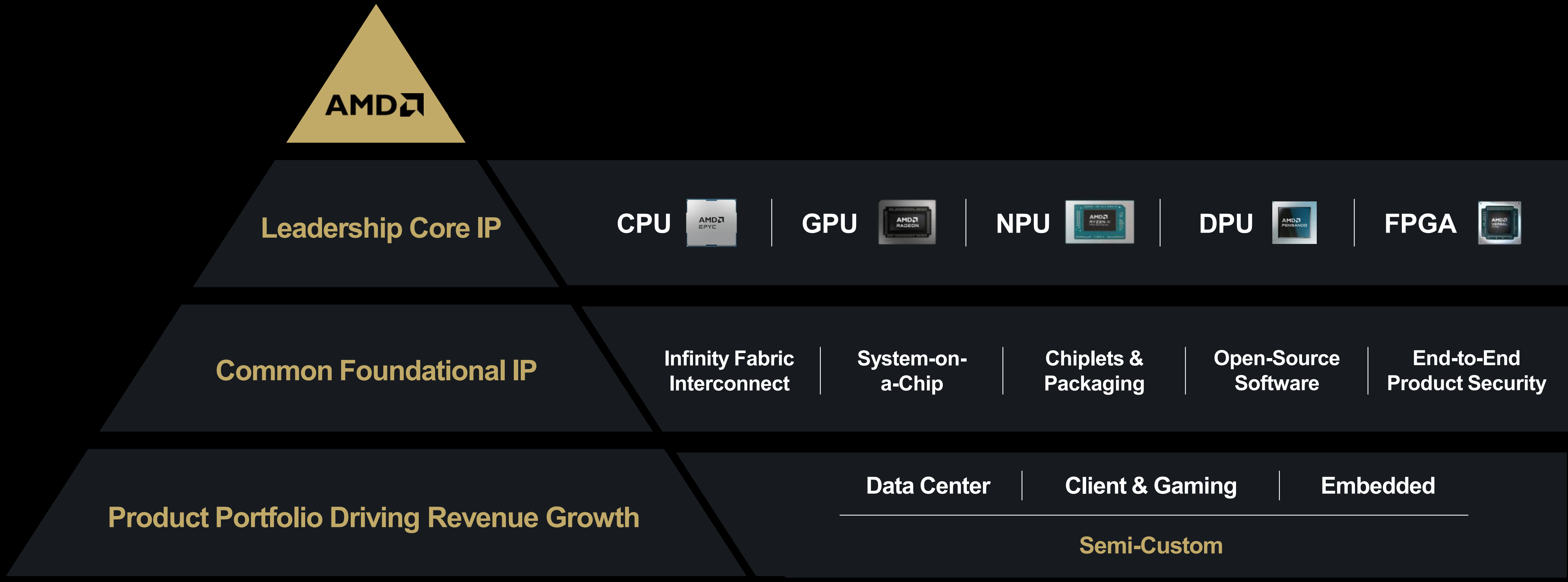
Common Foundational IP

Infinity Fabric Interconnect | System-on-a-Chip | Chiplets & Packaging | Open-Source Software | End-to-End Product Security

Product Portfolio Driving Revenue Growth

Data Center | Client & Gaming | Embedded

Industry's Broadest Solution Portfolio



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Product Portfolio Driving Revenue Growth

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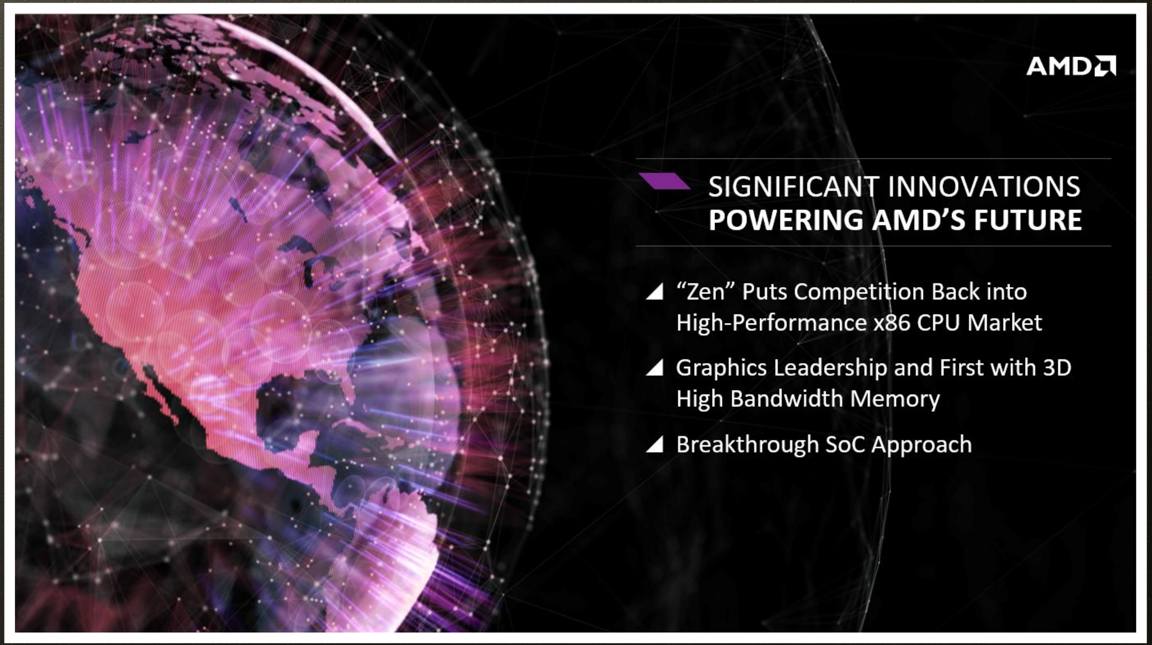
Semi-Custom

We Called the Play



SIGNIFICANT INNOVATIONS
POWERING AMD'S FUTURE

- "Zen" Puts Competition Back into High-Performance x86 CPU Market
- Graphics Leadership and First with 3D High Bandwidth Memory
- Breakthrough SoC Approach

Financial Analyst Day • 2015

We Delivered

Industry Leadership “Zen” x86 CPU

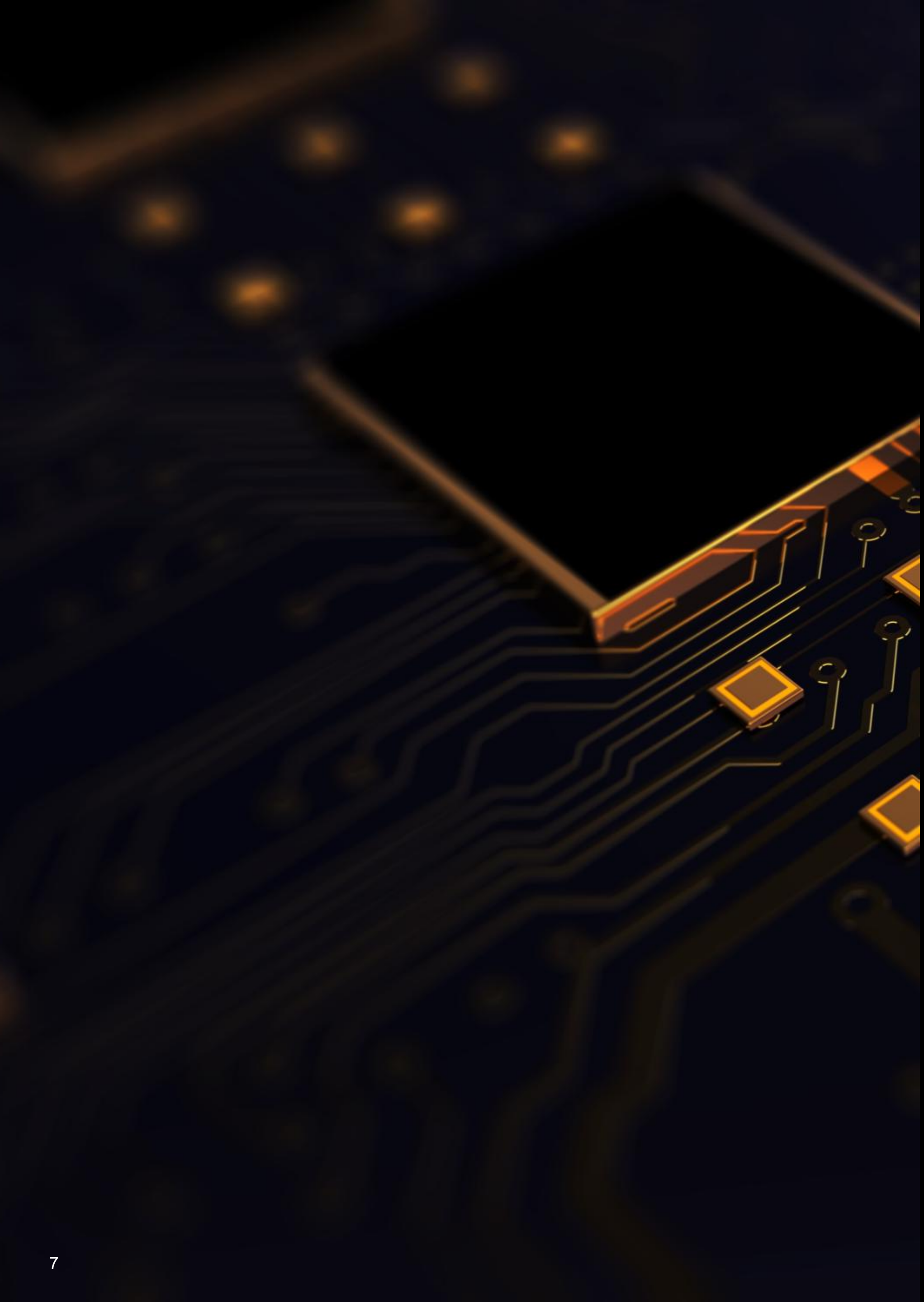
- Consistent Leadership Performance
- Chiplet Enabled Core Density Leadership
- High-Performance & Energy Optimized

AMD Instinct™ GPU with Leadership Inference Performance

- 2.5D Integrated HBM & 3D Chiplets Drove Memory & Compute Density Leadership
- TCO Advantages for Key AI Workloads

Breakthrough SoC Approach

- Scalable Infinity Fabric Enabled Modular Architecture
- First Chiplet Design Methodology



We Are Accelerating

Optimizing AI Across Portfolio

- **Compute Leadership Roadmap from Laptops to Rack-Scale**
- **Driving a Truly Open Software & Hardware AI Ecosystem**
- **SerDes, Optical & Networking Investments**
- **Confidential Computing for Trusted AI Processing**

Leadership CPU Core Roadmap

5nm • 4nm
Performance & Density

“Zen 4”
“Zen 4c”

AVX-512 AI ISA Support
Dual Core Design Points
Larger L2 Cache

4nm • 3nm
New Foundation

“Zen 5”
“Zen 5c”

Wider/Deeper Compute
Full 512 Bit AI Vectors
Re-optimized Cache Hierarchy

Industry-First 2nm
Extension of Leadership

“Zen 6”
“Zen 6c”

New AI Data Type Support
More AI Pipelines

Future Node
Next-Generation

“Zen 7”

New Matrix Engine
AI Data Format Expansion

2022 **2026**

*All roadmaps subject to change.

AMD Instinct™: Data Center GPU Architecture Roadmap

MI300

AI-Centric Design

Leadership 8-Stack HBM3 Capacity & Bandwidth

3.5D Chiplet Construction

Industry Standard Subsystem

MI325

Gen AI Performance

Increased HBM3e Capacity & Bandwidth

Higher Compute Throughput

Platform Compatibility

MI350 Series

Gen AI Inferencing & Training

Increased HBM3e Capacity & Bandwidth

Block Scaled AI Formats

Optimized Platform Solutions

MI400 Series

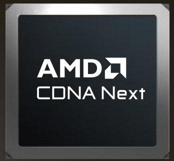
Rack-Scale Architecture

Increased HBM4 Capacity & Bandwidth

Expanded AI Formats with Higher Throughput

Standard-Based Rack-Scale Networking
(UALoE, UAL, UEC)

MI500 Series



Next-Gen Compute, Memory & Interconnect

2023

2026

*All roadmaps subject to change.

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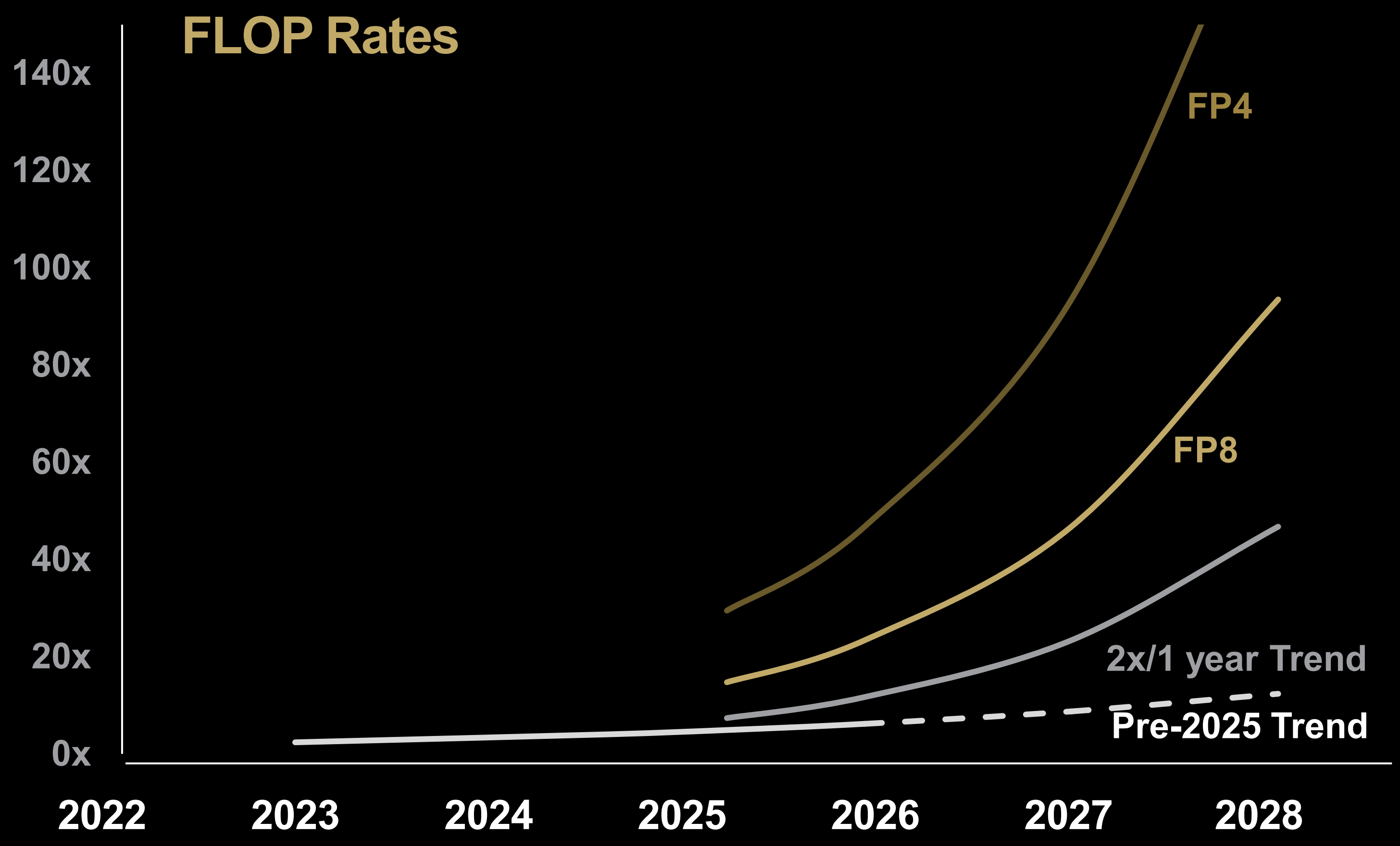
Accelerated GPU Performance Gains



- 2x Per Two Year Performance Trend Pre-2025 (16b Math)
- 2x Per One Year Performance Trend Commences in 2025
- AI-Optimized Low Precision Math (FP8 & FP4) Provide Even Higher Gains

*Based on AMD internal data.

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High-Speed SerDes Interconnect

40 Gb/s

First Server PCIe® 5.0

10s of Millions in Production

112 Gb/s

First 112G Ethernet FPGA

Leading Edge PCIe 6.0 PAM4

224 Gb/s

Leading Edge PCIe 7.0 PAM4

2026 “Helios” Rack Interconnect

Next Gen

Rack Transition Point

Copper & Optical Solutions

2022

2026

AMD Infinity Fabric Roadmap

3rd Generation

Up to 8-Way
GPU Connectivity

Coherent Memory for
Exascale Computing

PCIe® 5.0

4th Generation

Heterogeneous Chiplet

CXL™ 2.0 Memory Expansion

Support for Neural Engine

Introducing
5th Generation

Scale Up & Scale Out Leadership

Unified System Level Coherency

Standard Based Open Ecosystem
(UALink™, CXL 3.1 & UCIe™)

PCIe 6.0

Next-Gen

Continued Scale

2022

2026

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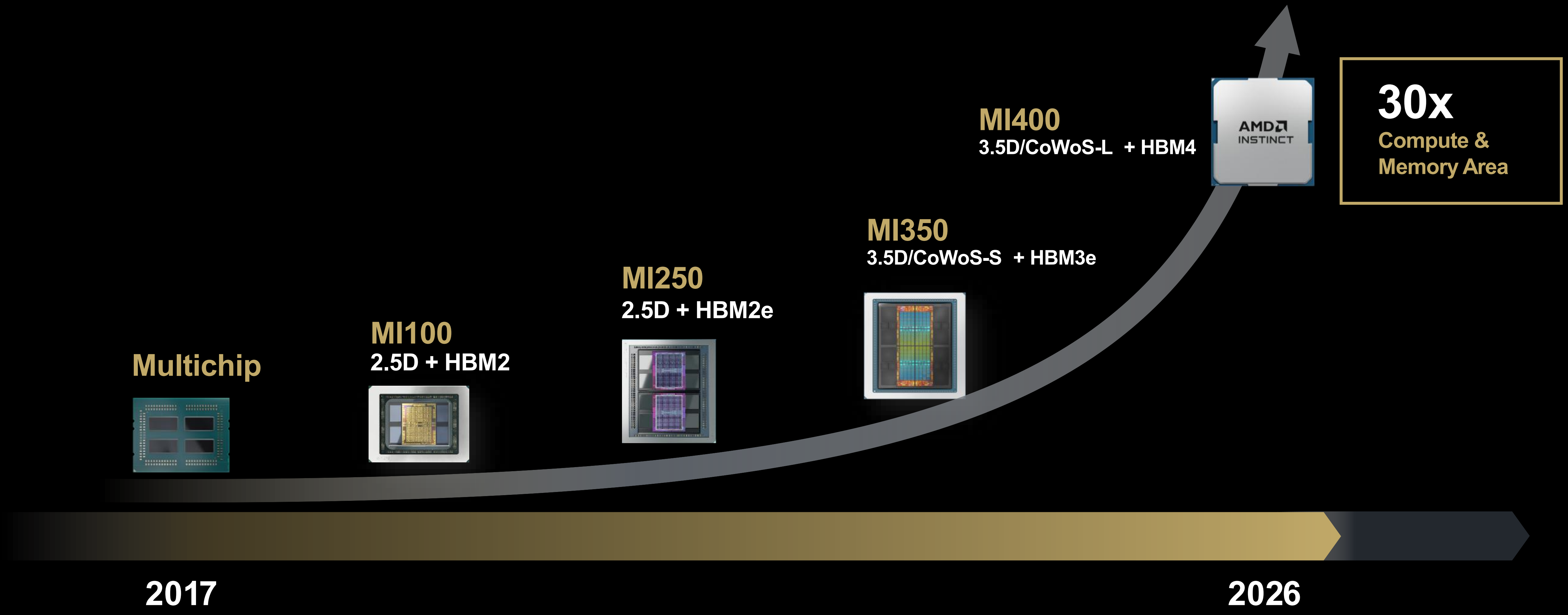
Chiplet & Packaging Leadership



Multichip

MI100
2.5D + HBM2

MI250
2.5D + HBM2e

MI350
3.5D/CoWoS-S + HBM3e

MI400
3.5D/CoWoS-L + HBM4

30x
Compute &
Memory Area

2017

2026

Solution Example

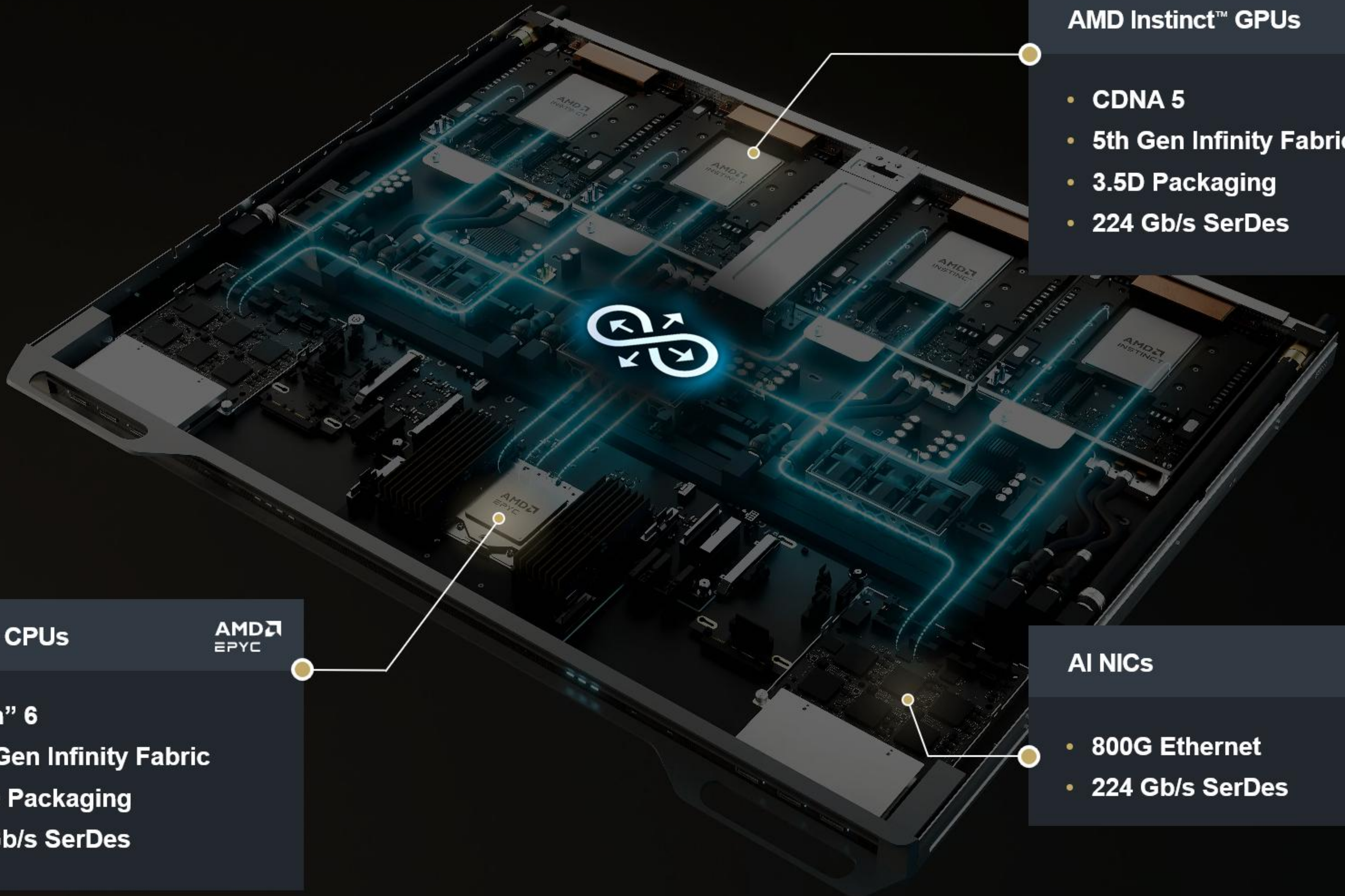
“Helios” Rack

Link at Rack-Scale – Scale Up & Scale Out

- **AMD Infinity Fabric for CPU to GPU link**
- **UALink™ Over Ethernet for Scale-Up**
- **UALink for GPU to AI Network Interface Card (NIC)**
- **AI NIC for Scale Out with Ultra Ethernet (UEC)**

Hardware-Software-Application Co-Optimization

- **AMD ROCm™ Inference & Training Scale with Compute & Communication**
- **Day-0 Optimization of Most Popular Models & Frameworks**



AMD Instinct™ GPUs

- CDNA 5
- 5th Gen Infinity Fabric at 112 Gb/s
- 3.5D Packaging
- 224 Gb/s SerDes

EPYC™ CPUs

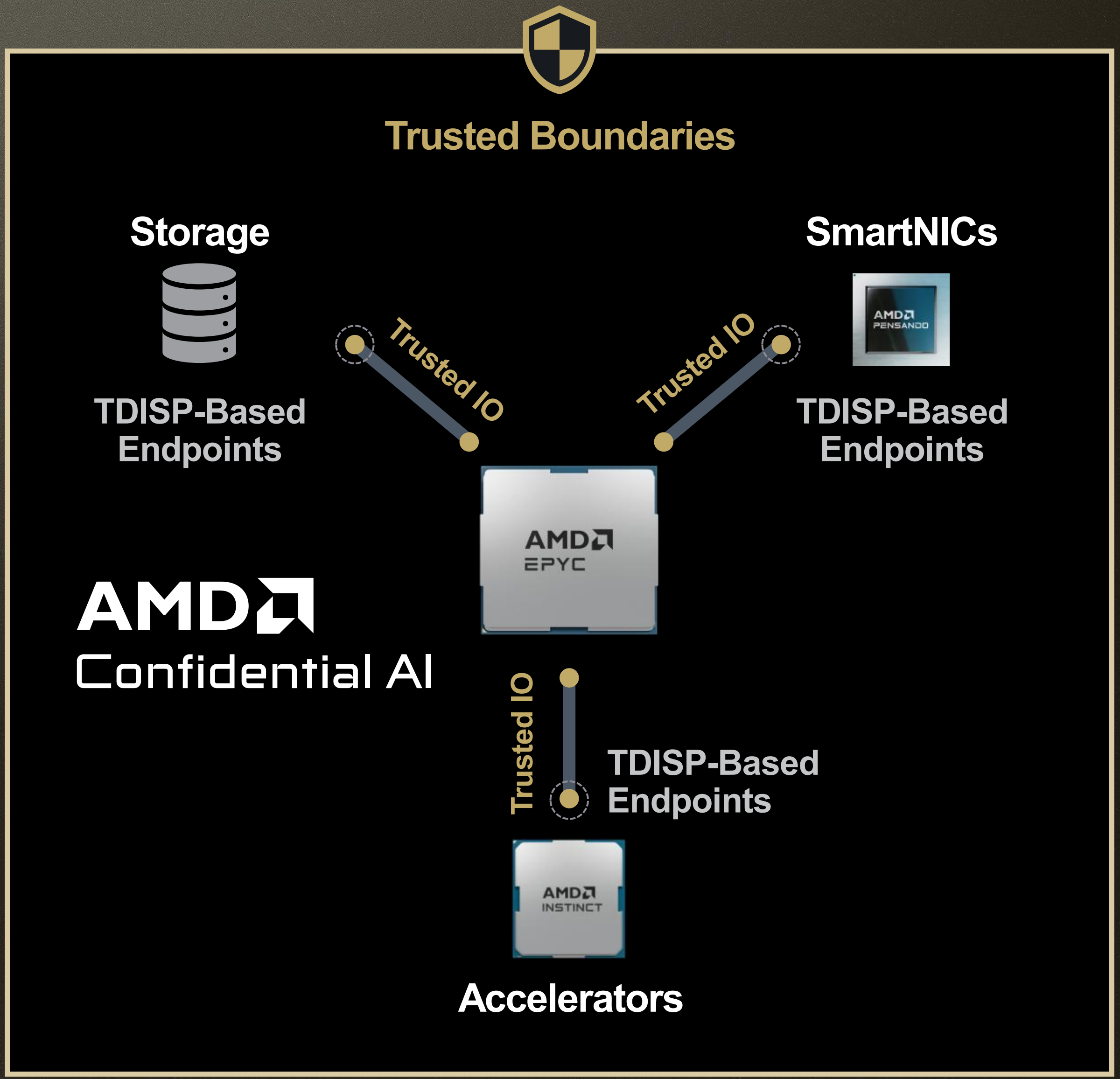
- “Zen” 6
- 5th Gen Infinity Fabric
- 2.5D Packaging
- 64 Gb/s SerDes

AI NICs

- 800G Ethernet
- 224 Gb/s SerDes

Trusted Computing

- Top Priority for IT Administrators: Protecting AI Models, Data & Weights
- Solution Enables End-to-End Encryption
- Confidential Computing Including Memory, Storage & I/O Devices



Gaming GPU Architecture Roadmap

Radeon™ RX 6000 Series

AI Foundation

Dot Product Acceleration

Raytracing

Radeon RX 7000 Series

1st Gen AI

Wave Matrix
Multiply Accumulate

Optimized Ray Accelerators

Radeon RX 9000 Series

2nd Gen AI

Dedicated AI
Optimized Pipelines

Advanced Raytracing

Next-Gen

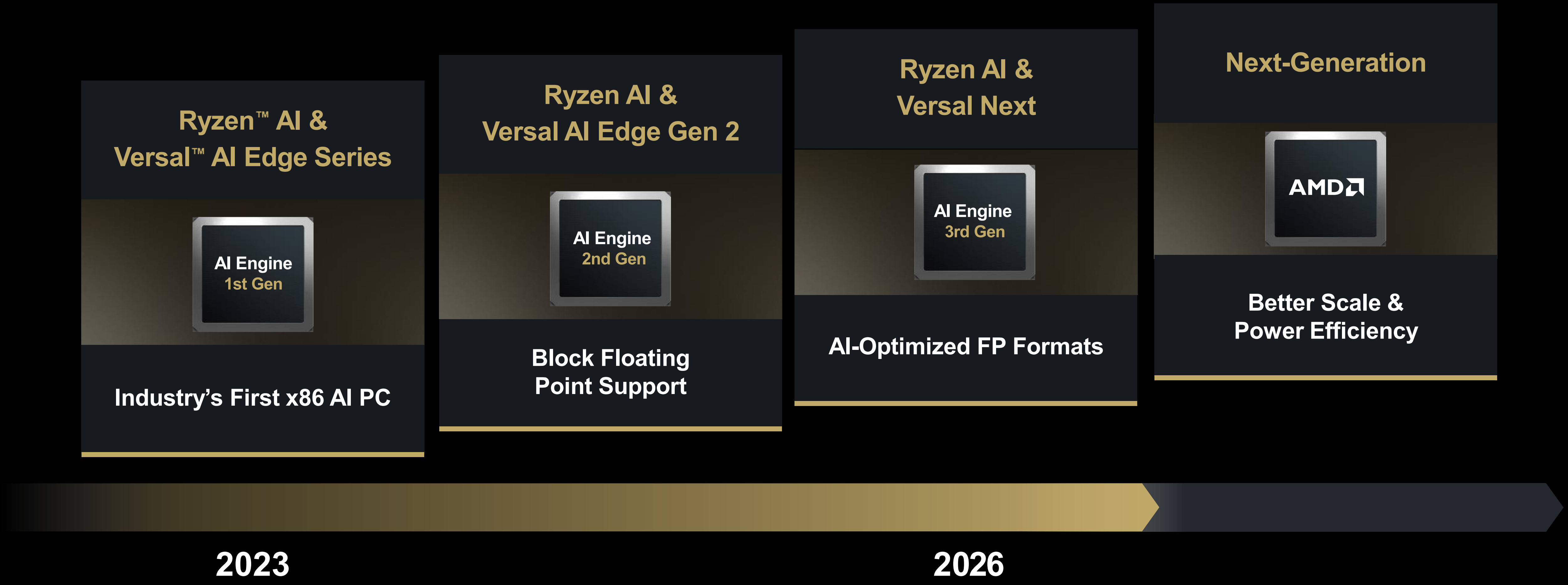
Next-Gen AI & Raytracing

2021

2025

*All roadmaps subject to change.

NPU Inference IP Roadmap for Client & Embedded



Ryzen™ AI & Versal™ AI Edge Series

AI Engine 1st Gen

Industry's First x86 AI PC

Ryzen AI & Versal AI Edge Gen 2

AI Engine 2nd Gen

Block Floating Point Support

Ryzen AI & Versal Next

AI Engine 3rd Gen

AI-Optimized FP Formats

Next-Generation

AMD

Better Scale & Power Efficiency

2023

2026

*All roadmaps subject to change.

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ROCm

AI Beyond the Data Center

One Software Stack Enables AI from Cloud to Edge

AI Models & Algorithms

PyTorch · Triton · Hugging Face · TensorFlow · ONNX · vLLM · SGL

Libraries

Compilers & Tools

Runtime


AMD Instinct™


EPYC™


Radeon™ AI


Ryzen™ AI


Embedded

Train Once • Infer Everywhere

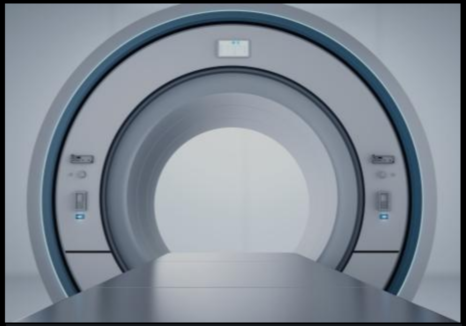
Investments for the Future

Data Center AI Compute Leadership

Rack-Scale GPU & Open Ecosystem

Agentic AI

Leadership CPUs to Accelerate Agents



Edge AI Explosion

Integrated CPU, GPU & NPU

Physical AI

Leadership Embedded FPGA, CPU & GPU

Quantum Computing

Hybrid Quantum with AMD Compute Cluster

Innovation for the AI Era

Product Leadership

Broadest IP Portfolio

Open Ecosystems

Relentless Execution

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